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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIL
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at80c32x2-3csum

Table 2. All SFRs with their address and their reset value

	Bit Addressable	Non Bit Addressable							
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	
F8h									FFh
F0h	B 0000 0000								F7h
E8h									EFh
E0h	ACC 0000 0000								E7h
D8 h									DFh
D0 h	PSW 0000 0000								D7h
C8 h	T2CON 0000 0000	T2MOD XXXX XX00	RCAP2L 0000 0000	RCAP2H 0000 0000	TL2 0000 0000	TH2 0000 0000			CFh
C0 h									C7h
B8h	IP XX00 0000	SADEN 0000 0000							BFh
B0h	P3 1111 1111							IPH XX00 0000	B7h
A8h	IE 0X00 0000	SADDR 0000 0000							AFh
A0h	P2 1111 1111		AUXR1 XXXX XXX0						A7h
98h	SCON 0000 0000	SBUF XXXX XXXX							9Fh
90h	P1 1111 1111								97h
88h	TCON 0000 0000	TMOD 0000 0000	TL0 0000 0000	TL1 0000 0000	TH0 0000 0000	TH1 0000 0000	AUXR XXXXXXXX0	CKCON XXXX XXX0	8Fh
80h	P0 1111 1111	SP 0000 0111	DPL 0000 0000	DPH 0000 0000				PCON 00X1 0000	87h
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	

Reserved 

Mnemonic	Pin Number			Type	Name and Function
	DIL	LCC	VQFP 1.4		
V _{SS}	20	22	16	I	Ground: 0V reference
V _{SS1}		1	39	I	Optional Ground: Contact the Sales Office for ground connection.
V _{CC}	40	44	38	I	Power Supply: This is the power supply voltage for normal, idle and power-down operation
P0.0-P0.7	39-32	43-36	37-30	I/O	<p>Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs. Port 0 pins must be polarized to V_{CC} or V_{SS} in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.</p>
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	
					<p>Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification.</p> <p>Alternate functions for Port 1 include:</p>
	1	2	40	I/O	T2 (P1.0): Timer/Counter 2 external count input/Clockout
	2	3	41	I	T2EX (P1.1): Timer/Counter 2 Reload/Capture/Direction Control
P2.0-P2.7	21-28	24-31	18-25	I/O	<p>Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX atDPTR). In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX atRi), port 2 emits the contents of the P2 SFR. Some Port 2 pins receive the high order address bits during EPROM programming and verification: P2.0 to P2.4</p>
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	
					<p>Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Port 3 also serves the special features of the 80C51 family, as listed below.</p>
	10	11	5	I	RXD (P3.0): Serial input port
	11	13	7	O	TXD (P3.1): Serial output port
	12	14	8	I	INT0 (P3.2): External interrupt 0

TS80C52X2 Enhanced Features

In comparison to the original 80C52, the TS80C52X2 implements some new features, which are:

- The X2 option
- The Dual Data Pointer
- The 4 level interrupt priority system
- The power-off flag
- The ONCE mode
- The ALE disabling
- Some enhanced features are also located in the UART and the Timer 2

X2 Feature

The TS80C52X2 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

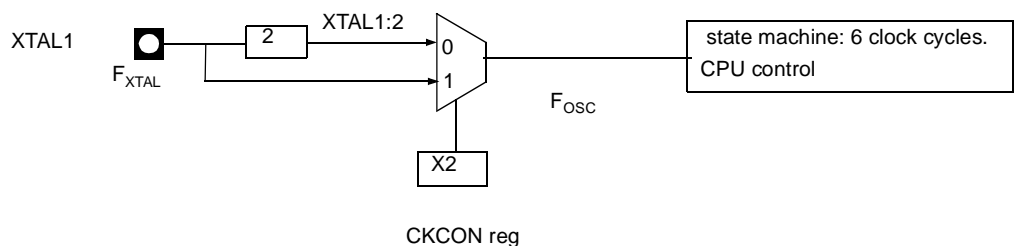
- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power
- Save power consumption while keeping same CPU power (oscillator power saving)
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes
- Increase CPU power by 2 while keeping same crystal frequency

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 1. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 2 shows the mode switching waveforms.

Figure 1. Clock Generation Diagram



Timer 2

The timer 2 in the TS80C52X2 is compatible with the timer 2 in the 80C52.

It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 5) and T2MOD register (See Table 6). Timer 2 operation is similar to Timer 0 and Timer 1. C/T2 selects $F_{OSC}/12$ (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.

Timer 2 has 3 operating modes: capture, autoreload and Baud Rate Generator. These modes are selected by the combination of RCLK, TCLK and CP/RL2 (T2CON), as described in the Atmel 8-bit Microcontroller Hardware description.

Refer to the Atmel 8-bit Microcontroller Hardware description for the description of Capture and Baud Rate Generator Modes.

In TS80C52X2 Timer 2 includes the following enhancements:

- Auto-reload mode with up or down counter
- Programmable clock-output

Auto-reload Mode

The Auto-reload mode configures timer 2 as a 16-bit timer or event counter with automatic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 4. In this mode the T2EX pin controls the direction of count.

When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.

When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution.

Figure 5. Clock-Out Mode $C/\overline{T2} = 0$

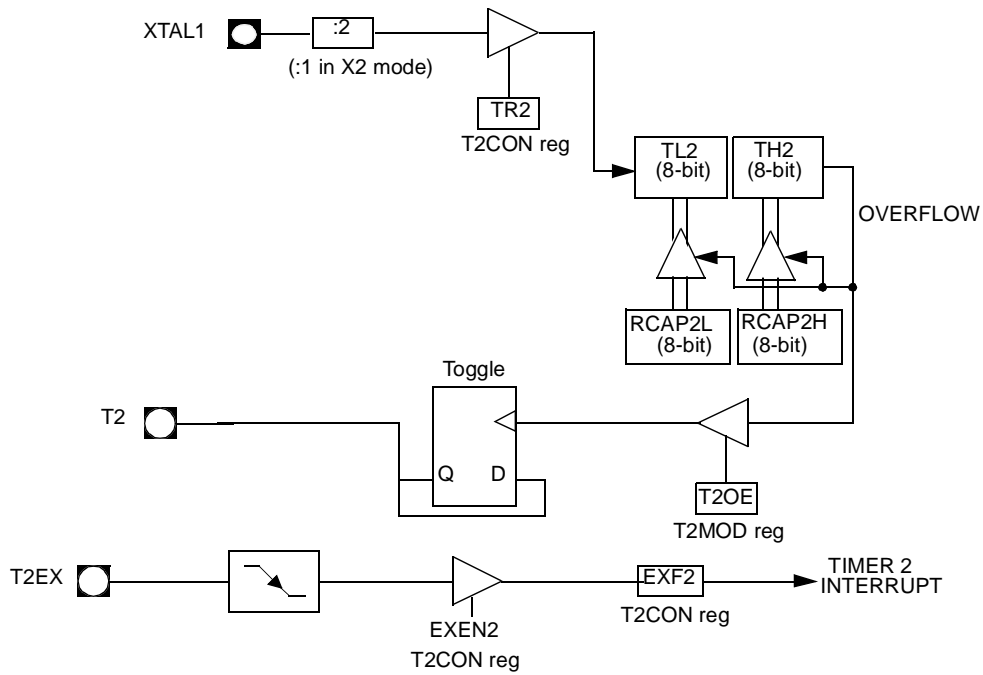


Table 6. T2MOD Register
T2MOD - Timer 2 Mode Control Register (C9h)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	T2OE	DCEN

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
1	T2OE	Timer 2 Output Enable bit Clear to program P1.0/T2 as clock input or I/O port. Set to program P1.0/T2 as clock output.
0	DCEN	Down Counter Enable bit Clear to disable timer 2 as up/down counter. Set to enable timer 2 as up/down counter.

Reset Value = XXXX XX00b
Not bit addressable

TS80C52X2 Serial I/O Port

The serial I/O port in the TS80C52X2 is compatible with the serial I/O port in the 80C52. It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous Receiver and Transmitter (UART) in three full-duplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates

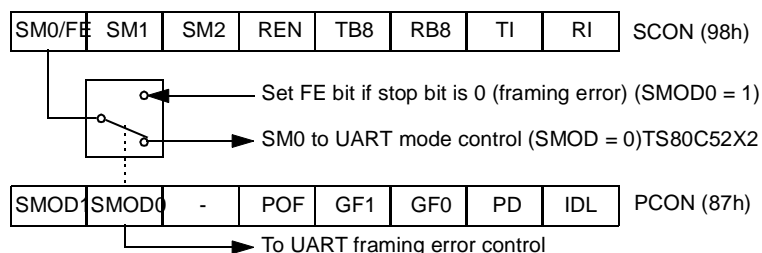
Serial I/O port includes the following enhancements:

- Framing error detection
- Automatic address recognition

Framing Error Detection

Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 6).

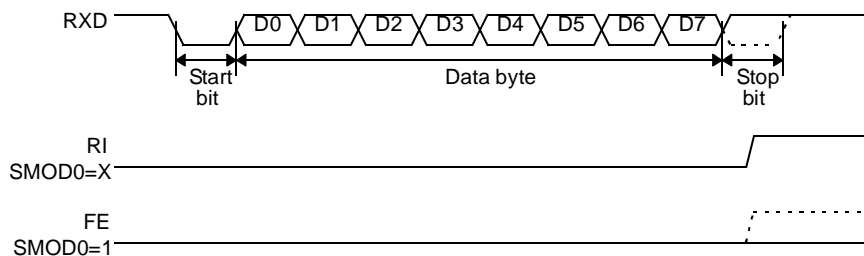
Figure 6. Framing Error Block Diagram



When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 9.) bit is set.

Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 7. and Figure 8.).

Figure 7. UART Timings in Mode 1



1111 0000b).

For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

```
SADDR 0101 0110b
SADEN 1111 1100b
Broadcast =SADDR OR SADEN1111 111Xb
```

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:SADDR1111 0001b
      SADEN1111 1010b
Broadcast1111 1X11b,
```

```
Slave B:SADDR1111 0011b
      SADEN1111 1001b
Broadcast1111 1X11b,
```

```
Slave C:SADDR=1111 0010b
      SADEN1111 1101b
Broadcast1111 1111b
```

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send an address FBh.

Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX XXXXb (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

Table 7. SADEN Register
SADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b

Not bit addressable

Table 8. SADDR Register
SADDR - Slave Address Register (A9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b

Not bit addressable



Table 9. SCON Register
SCON - Serial Control Register (98h)

7	6	5	4	3	2	1	0																									
FE/SM0	SM1	SM2	REN	TB8	RB8	TI	RI																									
Bit Number	Bit Mnemonic	Description																														
7	FE	Framing Error bit (SMOD0=1) Clear to reset the error state, not cleared by a valid stop bit. Set by hardware when an invalid stop bit is detected. SMOD0 must be set to enable access to the FE bit																														
	SM0	Serial port Mode bit 0 Refer to SM1 for serial port mode selection. SMOD0 must be cleared to enable access to the SM0 bit																														
6	SM1	Serial port Mode bit 1 <table><thead><tr><th>SM0</th><th>SM1</th><th>Mode</th><th>Description</th><th>Baud Rate</th></tr></thead><tbody><tr><td>0</td><td>0</td><td>0</td><td>Shift Register</td><td>$F_{XTAL}/12$ (/6 in X2 mode)</td></tr><tr><td>0</td><td>1</td><td>1</td><td>8-bit UART</td><td>Variable</td></tr><tr><td>1</td><td>0</td><td>2</td><td>9-bit UART</td><td>$F_{XTAL}/64$ or $F_{XTAL}/32$ (/32, /16 in X2 mode)</td></tr><tr><td>1</td><td>1</td><td>3</td><td>9-bit UART</td><td>Variable</td></tr></tbody></table>						SM0	SM1	Mode	Description	Baud Rate	0	0	0	Shift Register	$F_{XTAL}/12$ (/6 in X2 mode)	0	1	1	8-bit UART	Variable	1	0	2	9-bit UART	$F_{XTAL}/64$ or $F_{XTAL}/32$ (/32, /16 in X2 mode)	1	1	3	9-bit UART	Variable
SM0	SM1	Mode	Description	Baud Rate																												
0	0	0	Shift Register	$F_{XTAL}/12$ (/6 in X2 mode)																												
0	1	1	8-bit UART	Variable																												
1	0	2	9-bit UART	$F_{XTAL}/64$ or $F_{XTAL}/32$ (/32, /16 in X2 mode)																												
1	1	3	9-bit UART	Variable																												
5	SM2	Serial port Mode 2 bit / Multiprocessor Communication Enable bit Clear to disable multiprocessor communication feature. Set to enable multiprocessor communication feature in mode 2 and 3, and eventually mode 1. This bit should be cleared in mode 0.																														
4	REN	Reception Enable bit Clear to disable serial reception. Set to enable serial reception.																														
3	TB8	Transmitter Bit 8 / Ninth bit to transmit in modes 2 and 3. Clear to transmit a logic 0 in the 9th bit. Set to transmit a logic 1 in the 9th bit.																														
2	RB8	Receiver Bit 8 / Ninth bit received in modes 2 and 3 Cleared by hardware if 9th bit received is a logic 0. Set by hardware if 9th bit received is a logic 1. In mode 1, if SM2 = 0, RB8 is the received stop bit. In mode 0 RB8 is not used.																														
1	TI	Transmit Interrupt flag Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0 or at the beginning of the stop bit in the other modes.																														
0	RI	Receive Interrupt flag Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0, see Figure 7. and Figure 8. in the other modes.																														

Reset Value = 0000 0000b

Bit addressable

Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirety: the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occurred during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

Power-down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 10., PCON register).

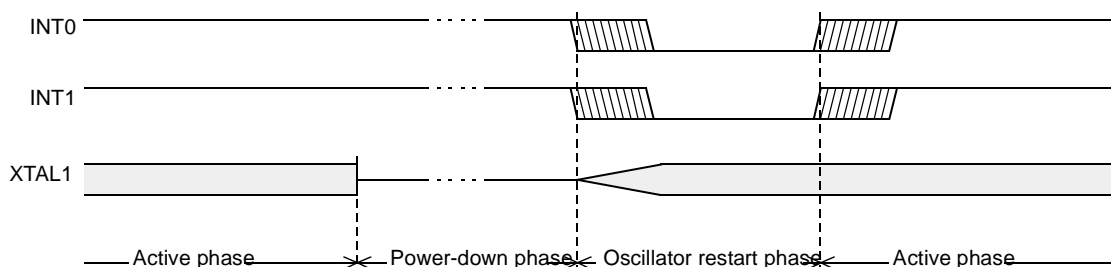
In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{INT0}$ and $\overline{INT1}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.

Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 10. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.

Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C52X2 into power-down mode.

Figure 10. Power-down Exit Waveform



Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does not affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

Note: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

Table 15. The State of Ports During Idle and Power-down Modes

Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Port Data ⁽¹⁾	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power Down	Internal	0	0	Port Data ⁽¹⁾	Port Data	Port Data	Port Data
Power Down	External	0	0	Floating	Port Data	Port Data	Port Data

Note: 1. Port 0 can force a "zero" level. A "one" will leave port floating.

ONCE™ Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C52X2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C52X2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and $\overline{\text{PSEN}}$ is high.
- Hold ALE low as RST is deactivated.

While the TS80C52X2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 16. External Pin Status during ONCE Mode

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull-up	Weak pull-up	Float	Weak pull-up	Weak pull-up	Weak pull-up	Active

EPROM Structure

The TS87C52X2 is divided in two different arrays:

- the code array: 8 Kbytes
- the encryption array: 64 bytes

In addition a third non programmable array is implemented:

- the signature array: 4 bytes

EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

Program Lock Bits

The three lock bits, when programmed according to Table 1., will provide different level of protection for the on-chip code and data.

Program Lock Bits				Protection Description
Security level	LB1	LB2	LB3	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, EA is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	P	U	Same as 2, also verify is disabled.
4	U	U	P	Same as 3, also external execution is disabled.

U: unprogrammed

P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

Signature Bytes

The TS80/87C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

EPROM Programming

Set-up modes

In order to program and verify the EPROM or to read the signature bytes, the TS87C52X2 is placed in specific set-up modes (See Figure 11.).

Control and program signals must be held at the levels indicated in Table 35.

Definition of terms

Address Lines: P1.0-P1.7, P2.0-P2.4 respectively for A0-A12

Data Lines: P0.0-P0.7 for D0-D7

Control Signals: RST, $\overline{\text{PSEN}}$, P2.6, P2.7, P3.3, P3.6, P3.7.

Program Signals: ALE/ $\overline{\text{PROG}}$, $\overline{\text{EA}}$ /VPP.

Table 20. EPROM Set-up Modes








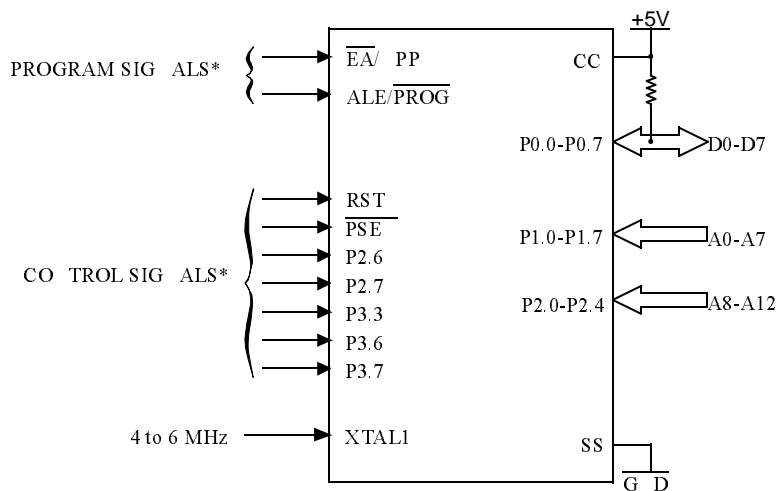
Mode	RST	PSEN	ALE/ PROG	$\overline{\text{EA}}$ / VPP	P2.6	P2.7	P3.3	P3.6	P3.7
Program Code data	1	0		12.75V	0	1	1	1	1
Verify Code data	1	0	1	1	0		0	1	1
Program Encryption Array Address 0-3Fh	1	0		12.75V	0	1	1	0	1
Read Signature Bytes	1	0	1	1	0		0	0	0
Program Lock bit 1	1	0		12.75V	1	1	1	1	1
Program Lock bit 2	1	0		12.75V	1	1	1	0	0
Program Lock bit 3	1	0		12.75V	1	0	1	1	0

Figure 11. Set-Up Modes Configuration



* See Table 31. for proper value on these inputs

Electrical Characteristics

Absolute Maximum Ratings⁽¹⁾

Ambient Temperature Under Bias:

C = commercial.....0°C to 70°C
 I = industrial-40°C to 85°C
 Storage Temperature -65°C to + 150°C
 Voltage on V_{CC} to V_{SS}.....-0.5V to + 7 V
 Voltage on V_{PP} to V_{SS}.....-0.5V to + 13 V
 Voltage on Any Pin to V_{SS}.....-0.5V to V_{CC} + 0.5V
 Power Dissipation 1 W⁽²⁾

- Notes: 1. Stresses at or above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating I_{cc} measurements under reset, which made sense for the designs where the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating I_{cc}:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = V_{CC}, RST = V_{SS}, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating I_{cc}.

DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.
 T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.

Table 22. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3 ⁽⁶⁾			0.3	V	I _{OL} = 100 μA ⁽⁴⁾
				0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
				1.0	V	I _{OL} = 3.5 mA ⁽⁴⁾
V _{OL1}	Output Low Voltage, port 0 ⁽⁶⁾			0.3	V	I _{OL} = 200 μA ⁽⁴⁾
				0.45	V	I _{OL} = 3.2 mA ⁽⁴⁾
				1.0	V	I _{OL} = 7.0 mA ⁽⁴⁾
V _{OL2}	Output Low Voltage, ALE, $\overline{\text{PSEN}}$			0.3	V	I _{OL} = 100 μA ⁽⁴⁾
				0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
				1.0	V	I _{OL} = 3.5 mA ⁽⁴⁾

DC Parameters for Low Voltage

$T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$; $V_{SS} = 0\text{ V}$; $V_{CC} = 2.7\text{ V}$ to 5.5 V ; $F = 0$ to 30 MHz .
 $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$; $V_{SS} = 0\text{ V}$; $V_{CC} = 2.7\text{ V}$ to 5.5 V ; $F = 0$ to 30 MHz .

Table 23. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		$0.2 V_{CC} - 0.1$	V	
V_{IH}	Input High Voltage except XTAL1, RST	$0.2 V_{CC} + 0.9$		$V_{CC} + 0.5$	V	
V_{IH1}	Input High Voltage, XTAL1, RST	$0.7 V_{CC}$		$V_{CC} + 0.5$	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 ⁽⁶⁾			0.45	V	$I_{OL} = 0.8\text{ mA}$ ⁽⁴⁾
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{\text{PSEN}}$ ⁽⁶⁾			0.45	V	$I_{OL} = 1.6\text{ mA}$ ⁽⁴⁾
V_{OH}	Output High Voltage, ports 1, 2, 3	$0.9 V_{CC}$			V	$I_{OH} = -10\text{ }\mu\text{A}$
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{\text{PSEN}}$	$0.9 V_{CC}$			V	$I_{OH} = -40\text{ }\mu\text{A}$
I_{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	μA	$V_{in} = 0.45\text{ V}$
I_{LI}	Input Leakage Current			± 10	μA	$0.45\text{ V} < V_{in} < V_{CC}$
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	μA	$V_{in} = 2.0\text{ V}$
R_{RST}	RST Pulldown Resistor	50	90 ⁽⁵⁾	200	$\text{k}\Omega$	
CIO	Capacitance of I/O Buffer			10	pF	$F_c = 1\text{ MHz}$ $T_A = 25^\circ\text{C}$
I_{PD}	Power Down Current		20 ⁽⁵⁾ 10 ⁽⁵⁾	50 30	μA	$V_{CC} = 2.0\text{ V}$ to 5.5 V ⁽³⁾ $V_{CC} = 2.0\text{ V}$ to 3.3 V ⁽³⁾
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			1 + 0.2 Freq (MHz) at 12MHz 3.4 at 16MHz 4.2	mA	$V_{CC} = 3.3\text{ V}$ ⁽¹⁾
I_{CC} operating	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			1 + 0.3 Freq (MHz) at 12MHz 4.6 at 16MHz 5.8	mA	$V_{CC} = 3.3\text{ V}$ ⁽⁸⁾
I_{CC} idle	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			0.15 Freq (MHz) + 0.2 at 12MHz 2 at 16MHz 2.6	mA	$V_{CC} = 3.3\text{ V}$ ⁽²⁾

- Notes:
- I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5\text{ ns}$ (see Figure 17.), $V_{IL} = V_{SS} + 0.5\text{ V}$, $V_{IH} = V_{CC} - 0.5\text{ V}$; XTAL2 N.C.; $\overline{\text{EA}} = \text{RST} = \text{Port } 0 = V_{CC}$. I_{CC} would be slightly higher if a crystal oscillator used..
 - Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5\text{ ns}$, $V_{IL} = V_{SS} + 0.5\text{ V}$, $V_{IH} = V_{CC} - 0.5\text{ V}$; XTAL2 N.C.; Port 0 = V_{CC} ; $\overline{\text{EA}} = \text{RST} = V_{SS}$ (see Figure 15.).
 - Power Down I_{CC} is measured with all output pins disconnected; $\overline{\text{EA}} = V_{SS}$, PORT 0 = V_{CC} ; XTAL2 NC.; RST = V_{SS} (see Figure 16.).
 - Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL} s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.
 - Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
 - Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
Maximum I_{OL} per port pin: 10 mA
Maximum I_{OL} per 8-bit port:

Table 27. AC Parameters for Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T	25		33		25		50		33		ns
T _{LHLL}	40		25		42		35		52		ns
T _{AVLL}	10		4		12		5		13		ns
T _{LLAX}	10		4		12		5		13		ns
T _{LLIV}		70		45		78		65		98	ns
T _{LLPL}	15		9		17		10		18		ns
T _{PLPH}	55		35		60		50		75		ns
T _{PLIV}		35		25		50		30		55	ns
T _{PXIX}	0		0		0		0		0		ns
T _{PXIZ}		18		12		20		10		18	ns
T _{AVIV}		85		53		95		80		122	ns
T _{PLAZ}		10		10		10		10		10	ns

Table 28. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T _{LHLL}	Min	2 T - x	T - x	10	8	15	ns
T _{AVLL}	Min	T - x	0.5 T - x	15	13	20	ns
T _{LLAX}	Min	T - x	0.5 T - x	15	13	20	ns
T _{LLIV}	Max	4 T - x	2 T - x	30	22	35	ns
T _{LLPL}	Min	T - x	0.5 T - x	10	8	15	ns
T _{PLPH}	Min	3 T - x	1.5 T - x	20	15	25	ns
T _{PLIV}	Max	3 T - x	1.5 T - x	40	25	45	ns
T _{PXIX}	Min	x	x	0	0	0	ns
T _{PXIZ}	Max	T - x	0.5 T - x	7	5	15	ns
T _{AVIV}	Max	5 T - x	2.5 T - x	40	30	45	ns
T _{PLAZ}	Max	x	x	10	10	10	ns

Table 30. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T_{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDV}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T_{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T_{AVWL}	75		47		80		70		103		ns
T_{QVWX}	10		7		15		5		13		ns
T_{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

Table 37. Possible Ordering Entries (Continued)

Part Number ⁽³⁾	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT80C52X2zzz-3CSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PDIL40	Stick
AT80C52X2zzz-SLSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PLCC44	Stick
AT80C52X2zzz-RTLUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	VQFP44	Tray
AT80C52X2zzz-3CSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	PDIL40	Stick
AT80C52X2zzz-SLSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	PLCC44	Stick
AT80C52X2zzz-RTLUV	8K ROM	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	VQFP44	Tray
TS87C52X2-MCA	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-MCB	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	PLCC44	Stick
TS87C52X2-MCC	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2-MCE	8K OTP	5V ±10%	Commercial	40 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2-LCA	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-LCB	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PLC44	Stick
TS87C52X2-LCC	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2-LCE	8K OTP	2.7 to 5.5V	Commercial	30 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2-VCA	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	PDIL40	Stick
TS87C52X2-VCB	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	PLCC44	Stick
TS87C52X2-VCC	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	PQFP44	Tray
TS87C52X2-VCE	8K OTP	5V ±10%	Commercial	60 MHz ⁽³⁾	VQFP44	Tray
TS87C52X2-MIA	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-MIB	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	PLCC44	Stick
TS87C52X2-MIC	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2-MIE	8K OTP	5V ±10%	Industrial	40 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2-LIA	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PDIL40	Stick
TS87C52X2-LIB	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PLCC44	Stick
TS87C52X2-LIC	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	PQFP44	Tray
TS87C52X2-LIE	8K OTP	2.7 to 5.5V	Industrial	30 MHz ⁽¹⁾	VQFP44	Tray
TS87C52X2-VIA	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	PDIL40	Stick
TS87C52X2-VIB	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	PLCC44	Stick
TS87C52X2-VIC	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	PQFP44	Tray
TS87C52X2-VIE	8K OTP	5V ±10%	Industrial	60 MHz ⁽³⁾	VQFP44	Tray

Table 37. Possible Ordering Entries (Continued)

Part Number ⁽³⁾	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT87C52X2-3CSUM	8K OTP	5V ±10%	Industrial & Green	40 MHz ⁽¹⁾	PDIL40	Stick
AT87C52X2-SLSUM	8K OTP	5V ±10%	Industrial & Green	40 MHz ⁽¹⁾	PLCC44	Stick
AT87C52X2-RLTUM	8K OTP	5V ±10%	Industrial & Green	40 MHz ⁽¹⁾	VQFP44	Tray
AT87C52X2-3CSUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PDIL40	Stick
AT87C52X2-SLSUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	PLCC44	Stick
AT87C52X2-RLTUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz ⁽¹⁾	VQFP44	Tray
AT87C52X2-3CSUV	8K OTP	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	PDIL40	Stick
AT87C52X2-SLSUV	8K OTP	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	PLCC44	Stick
AT87C52X2-RLTUV	8K OTP	5V ±10%	Industrial & Green	60 MHz ⁽³⁾	VQFP44	Tray

- Notes:
1. 20 MHz in X2 Mode.
 2. Tape and Reel available for SL, PQFP and RL packages
 3. 30 MHz in X2 Mode.